 Thickness Measurement on Ti, Au, Pd, and Cr using PVD75 E-beam Evaporator

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**Keywords**
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Prepared by Dhruv Turakhia (6/5/2015)

Deposition Rate: 2 Å/sec
Final Thickness Set Point: 300 nm
Default Tooling Factor Xtal 1: 54
Default Tooling Factor Xtal 2: 100
Thickness measurement: P7 Stylus Profiler

**Ti deposition**
Measured thickness: 306.0 ± 9.6 nm

**Au deposition**
Measured thickness: 237.6 ± 4.2 nm

**Pd deposition**
Measured thickness: 265.5 ± 17.8 nm

**Cr deposition**
Measured thickness: 407.2 ± 16.5 nm